

## Highlights

## Excellent Quality and Superior Service

- ▶ **State-of-the-Art Fully Automatic Dual Feed Grinder & Polisher Systems**
- ▶ **Class 100 Work Stations in Clean Room Environment**
- ▶ **Production Volumes**
  - Thousands of wafers/wk
  - Prototype and low volumes also handled
- ▶ **Capabilities**
  - Ultra-thin wafers <100µm
  - Precision, 1.5µm TTV
  - Bumped wafers
  - 3 to 12 inch wafer diameters
  - Unmatched stress relief
  - Silicon, SiGe, Sapphire, Pyrex, and other materials.
- ▶ **Specialty Grinding**
  - Partial wafers
  - Gold back removal
  - PZT
  - Resin
  - Silicon on glass
  - Stacked wafers

**CORWIL** will thin and polish your wafers ranging from 3 inches to the most modern 12 inch (300mm) diameter. CORWIL specializes in Ultra-thin Precision Wafer Thinning and Polishing down to 75 microns for 8 inch wafers holding TTV (total thickness variation) to less than 1.5 microns within one wafer. CORWIL routinely handles bumped wafers of wide-ranging bump heights and pitches and stocks a diverse assortment of front side tapes to provide the best protection for your wafers during processing.

- **Wafer Thinning** - Fully Automatic World Class Disco Grinder systems handle wafers ranging from 3 to 8 inches as well as partial wafers. CORWIL's standard 2000 grit fine finish results in surface roughness of less than 1 micron sub-surface damage. For BSM (backside metallization) preparation or other applications, CORWIL's 1200 grit finish produces excellent results. CORWIL holds all wafers per lot to less than ±3 micron variation.
- **Micro-Grind** - For applications requiring stress relief and/or ultra-thin grinding to <100 microns, CORWIL's proprietary Micro-Grind finish produces less surface roughness, less warpage and greater die strength than standard backgrinding processes.
- **Wafer Polishing** - For the ultimate in wafer stress relief, CORWIL's state-of-the-art Dry Polish Technology produces superior product yield for all wafers including the ultra-thin (<100 µm) wafers used in smart card and stacked die applications. This process greatly reduces wafer breakage and warpage while improving die strength by minimizing or eliminating backside chipping and micro cracks. CORWIL's Dry Polish Technology is an improvement over Plasma Etch, Chemical Etch and CMP processes and is an environmentally friendly, chemical-free and slurry-free process.
- **Quick Turn Service** - Need it yesterday? CORWIL's 2 and 4-hour quick-turn service and on-time delivery is unmatched in the industry. Standard turn is 48 hrs.
- **CORWIL** has built its reputation providing customers with:  
*excellent quality and superior service*

## Contact Us At:

CORWIL Technology Corporation  
1635 McCarthy Boulevard  
Milpitas, CA 95035-7415  
Phone: 408-321-6404  
Fax: 408-321-6407  
E-mail: [info@corwil.com](mailto:info@corwil.com)  
Web: <http://www.corwil.com>



DSCC QML Listed  
(Qualified Manufacturers List)  
MIL-STD-883 DSCC Suitability